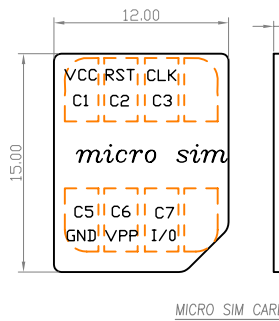
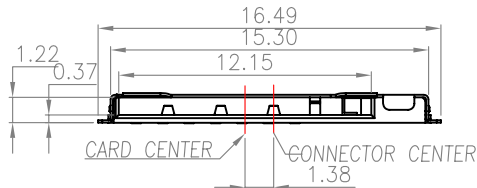
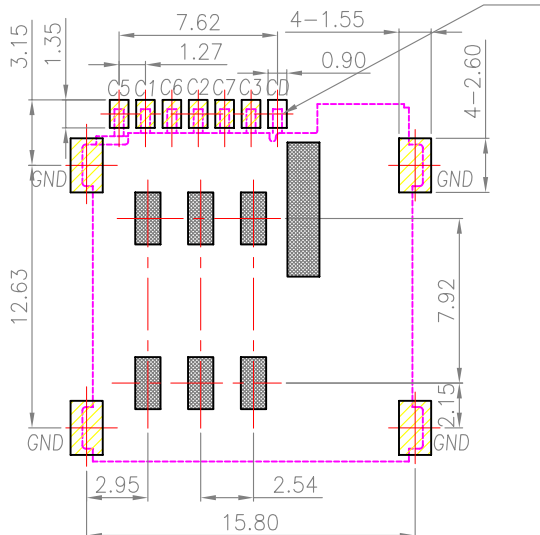


1. 此PIN为CD-PIN, 此PIN无须时不需要设计PCB焊盘。
2. 此PIN为CD-PIN, 支持热插拔, 有须要可设计此功能。



C1:VCC
C2:RST
C3:CLK
C4:RESERVED
C5:GND
C6:VPP
C7:I/O
C8:RESERVED

Specification

MATERIAL:

Insulator: High Temperature Thermoplastic, UL 94V-0.
Contact: Copper Alloy

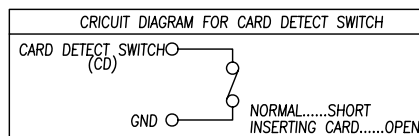
PLATING:

Contact: Plated 50u'' Ni Overall Contact Au II
Shell: Plated 50u'' Ni Overall
Plated 1u''Au Selective Contact Area

Electrical:

Current Rating :0.5mA AC/DC max.
Voltage Rating :125V AC/DC
Ambient Temperature Range :-20° C~+60° C
Storage Temperature Range :-40° C~+70° C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100mΩ max.
Insulation Resistance:1000MΩ min./500VDC
Mating Cycles:10,000 Insertions
产品耐温温度: 260° C ° C $SCL 70^{\circ} C$ $SCL 70^{\circ} C$

■ CIRCUIT TRACE KEEP OUT AREA
■ SMT SOLDER AREA
THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.
RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05



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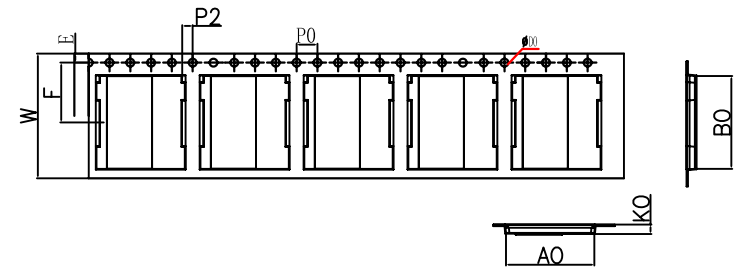
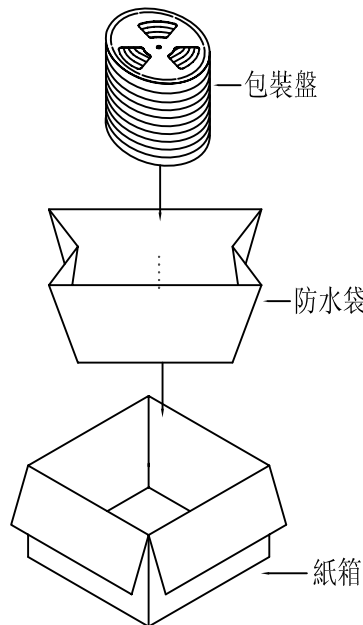
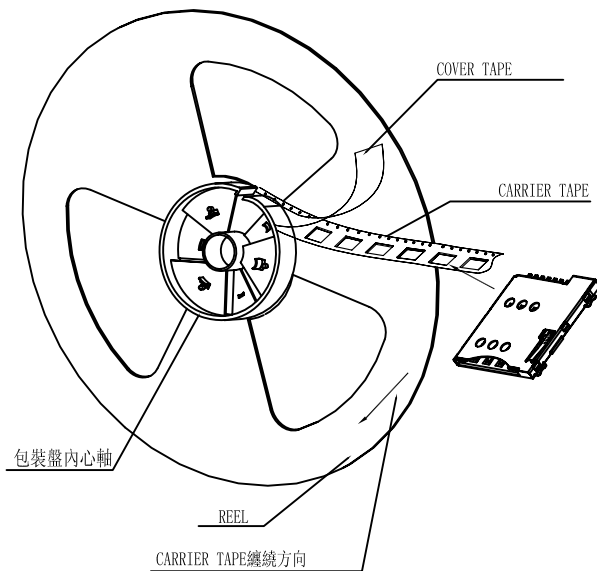
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X: ±2' X.X' ±0.5'	DRAWN BY : 吴迪	DATE : 2013-11-28	PART NAME: MICRO SIM PUSH 6+1	
	CHECKED BY: 马跃	DATE : 2013-11-28	PART NO.	HYC13-SIM07-135
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2013-11-28	MOLD NO.	
			DRAW NO:	HYC-SIM13112801
			SHEET NO.	1 OF 2

包裝作業規範

REEL(料盤)	509-00004
TYPE(卷盤)下帶	508-00017
TYPE(卷盤)上帶	512-00009
紙箱料號	501-00009

包裝作業圖示及說明 (PACKING OPERATION DIAGRAM & INSTRUCTION)

- 一.
- 1) 將成品一一放入包裝盤內, 依同一方向放入.
 - 2) 包裝時, 如圖所示.
 - 3) 一個包裝盤放置1000個成品.
- 二.
- 1) 一只紙箱可放置5個包裝盤.
 - 2) 一只紙箱可放5000PCS的成品.
 - 3) 將成品放入包裝盤內包裝完後再裝箱.
- 三.
- 1) REEL載帶尺寸圖.



ITEM	W	A0	B0	K0	P	F	E	S0	D0	P0	P2	T
DIM	24.00±0.10	17.0±0.10	17.85±0.10	2.0±0.10	20.0±0.10	11.50±0.10	1.75±0.10	0.00±0.10	1.50±0.10	4.00±0.10	2.00±0.10	0.30±0.10
ALTERNATE												

产品单重: 0.6g
 每盘单重: 800g
 每箱单重: 4100g (5000PCS)

HOAU 深圳市华宇创精密电子有限公司

TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.' ±2' X.X' ±0.5'	DRAWN BY : 吴迪	DATE : 2013-11-28	PART NAME: MICRO SIM PUSH 6+1	
	CHECKED BY: 马跃	DATE : 2013-11-28	PART NO. HYC13-SIM07-135	MOLD NO. /
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱国夷	DATE : 2013-11-28	DRAW NO: HYC-SIM13112801	SHEET NO. 2 OF 2